

**ESTABLISHMENT OF RIGHT OF ASSIGNEE TO TAKE ACTION  
AND  
REVOCATION AND POWER OF ATTORNEY**

To the Commissioner of Patents and Trademarks:

The undersigned is empowered to act on behalf of the assignee indicated below (the "Assignee"). The original assignment of the attached application for Letters Patent for the invention in POLISHING PAD  
AND SEMICONDUCTOR DEVICE MANUFACTURING METHOD from the inventors to the Assignee is being submitted herewith for recordation by the Assignment Branch. A true copy of this Assignment is attached hereto. This Assignment represents the entire chain of title of this invention from the Inventor(s) to the Assignee. I have reviewed this Assignment, and to the best of the Assignee's knowledge and belief, the Assignee is the owner of the entire right, title, and interest in the above-referenced application.

I declare that all statements made herein of my own knowledge are true, and that all statements made upon information and belief are believed to be true, and further, that these statements were made with the knowledge that willful, false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001, and that willful, false statements may jeopardize the validity of the application, or any patent issuing thereon.

The undersigned hereby revokes any previous powers of attorney in the subject application, and hereby appoints the registrants of Knobbe, Martens, Olson & Bear, LLP, 2040 Main Street, Fourteenth Floor, Irvine, California 92614, Telephone (949) 760-0404, **Customer No. 20,995**, as its attorneys with full power of substitution and revocation to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected herewith. This appointment is to be to the exclusion of the inventor(s) and his attorney(s) in accordance with the provisions of 37 C.F.R. § 3.71.

Please use **Customer No. 20,995** for all communications.

Assignee: TOYO TIRE & RUBBER CO., LTD.

By: Yoshio KATAOKA  
Yoshio KATAOKA

Title: President

Address: 17-18, Edobori 1-chome, Nishi-ku,  
Osaka-shi, Osaka 550-8661 Japan

Dated: August 30, 2006

## ASSIGNMENT

WHEREAS, I/WE (1) Tetsuo SHIMOMURA,

a Japanese citizen, residing at c/o Toyo Boseki Kabushiki Kaisha Research Center, 1-1  
Katata 2-chome, Ohtsu-shi, Shiga 520-0292 Japan,

(2) Masahiko NAKAMORI,

a Japanese citizen, residing at c/o Toyo Boseki Kabushiki Kaisha Research Center, 1-1  
Katata 2-chome, Ohtsu-shi, Shiga 520-0292 Japan,

(3) Takatoshi YAMADA,

a Japanese citizen, residing at c/o Toyo Boseki Kabushiki Kaisha Research Center, 1-1  
Katata 2-chome, Ohtsu-shi, Shiga 520-0292 Japan,

(4) Kazuyuki OGAWA,

a Japanese citizen, residing at c/o Toyo Tire & Rubber Co., Ltd., 17-18, Edobori 1-chome  
Nishi-ku, Osaka-shi, Osaka 550-8661 Japan,

(5) Atsushi KAZUNO,

a Japanese citizen, residing at c/o Toyo Tire & Rubber Co., Ltd., 17-18, Edobori 1-chome  
Nishi-ku, Osaka-shi, Osaka 550-8661 Japan,

(6) Masahiro WATANABE,

a Japanese citizen, residing at c/o Toyo Tire & Rubber Co., Ltd., 17-18, Edobori 1-chome  
Nishi-ku, Osaka-shi, Osaka 550-8661 Japan,

hereinafter referred to as Assignor (collectively if more than one inventor is listed above), have invented certain new and useful improvements in POLISHING PAD AND SEMICONDUCTOR DEVICE MANUFACTURING METHOD, the specification of which:

(a) ☒ was executed on even date herewith;

(b) ☐ was filed on \_\_\_\_\_ as o Application No. 0 \_\_\_\_\_

or o Express Mail No \_\_\_\_\_, as Application No. not yet known

and was amended on \_\_\_\_\_ (if applicable); or

(c) ☐ was described and claimed in PCT International Application No. \_\_\_\_\_ filed on

\_\_\_\_\_ and as amended under PCT Article 19 on

\_\_\_\_\_ (if any) and/or under PCT Article 34 on

\_\_\_\_\_ (if any).

AND WHEREAS, Toyo Tire & Rubber Co., Ltd., with its principal place of business at 17-18, Edobori 1-chome, Nishi-ku, Osaka-shi, Osaka 550-8661 Japan (hereinafter referred to as Assignee) desires to acquire the entire right, title, and interest in and to the said improvements with respect to the United States of America, its territories and possessions.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, Assignor hereby acknowledges that it has sold, assigned, transferred and set over, and by these presents does hereby sell, assign, transfer and set over, unto Assignee, its successors, legal representatives and assigns, the entire right, title, and interest in the United States of America, and its territories and possessions in, to and under said improvements, and any Patent Applications in the United States of America and all divisions, renewals and continuations thereof, and all Patents of the United States of America which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions; and Assignor hereby authorizes and requests the Commissioner of Patents of the United States of America to issue all Patents for said improvements to Assignee, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND ASSIGNOR HEREBY covenants and agrees that it will communicate to Assignee, its successors, legal representatives and assigns, any facts known to it respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in the United States of America.

IN TESTIMONY WHEREOF, Assignor intending to be legally bound has hereunto affixed its signature.

This 30th day of August, 2006

Tetsuo Shimomura  
Signature of Tetsuo SHIMOMURA

This 30th day of August, 2006

Masahiko Nakamori  
Signature of Masahiko NAKAMORI

This 30th day of August, 2006

Takatoshi Yamada  
Signature of Takatoshi YAMADA

This 30th day of August, 2006

Kazuyuki Ogawa  
Signature of Kazuyuki OGAWA

This 30th day of August, 2006

Atsushi Kazuno  
Signature of Atsushi KAZUNO

This 30th day of August, 2006

Masahiro Watanabe  
Signature of Masahiro WATANABE

Witnessed by:

Kenichi Fukui  
Kenichi FUKUI